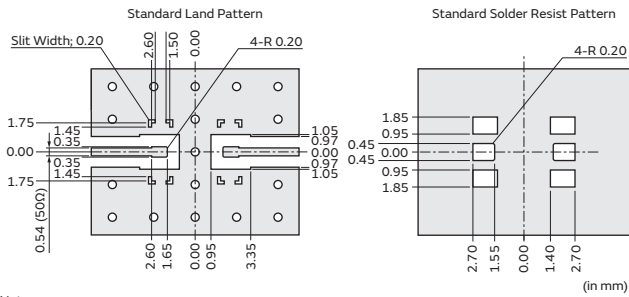


Land Pattern



- Note:
1. PCB Material; FR4 Glass-Epoxy, h=0.30mm (or 0.10mm x 3Layers.)
 2. Hatched sections show the circuit patterns or the solder-masking pattern.
 3. The bottom Surface is Ground Plane.
 4. To place a ground plane at 0.3mm from the top surface is recommended. Less distance may result in variation of the operating frequency due to stray capacitance.

Notice (Soldering)

Soldering Conditions

1. Reflow Soldering

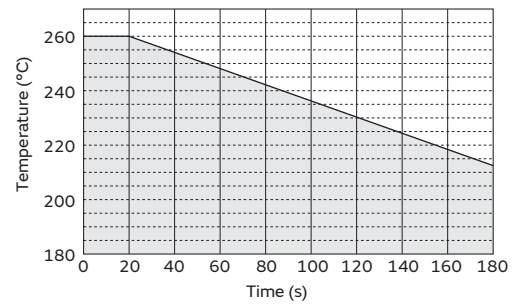
Soldering must be carried out without exceeding the allowable soldering temperature and time shown within the shaded area of Figure "Allowable Temperature and Time of Reflow Soldering". It is allowed to be reflow soldered up to twice with this condition. The standard soldering conditions are shown in Figure "Reflow Soldering Standard Conditions".

2. Soldering by Soldering Iron

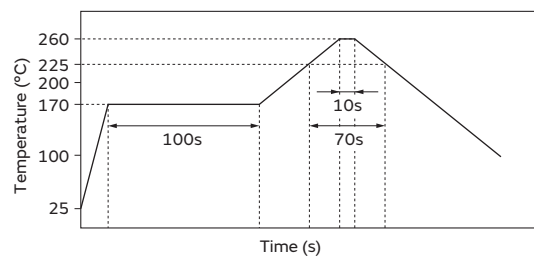
Soldering by soldering iron should be carried out in accordance to the following conditions.

Pre-heating	Temperature	150°C
	Time	60 s to 120 s
Soldering	Temperature (at the tip of the soldering iron)	less than 350°C \pm 3°C
	Time	less than 5 s
Soldering iron		60W max.

Allowable Temperature and Time of Reflow Soldering



Reflow Soldering Standard Conditions



Measuring Point of Temperature: In-Out Terminals of Device
 Reflow Soldering : Both Convection and Infrared Rays
 : Hot Air